

MOSFET - N-Channel, UniFET™

250 V, 33 A, 94 m Ω

FDPF33N25T

Description

UniFET™ MOSFET is **onsemi**'s high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on–state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.

Features

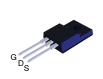
- $R_{DS(on)} = 94 \text{ m}\Omega \text{ (Max.)} @ V_{GS} = 10 \text{ V}, I_D = 16.5 \text{ A}$
- Low Gate Charge (Typ. 36.8 nC)
- Low C_{rss} (Typ. 39 pF)
- 100% Avalanche Tested

Applications

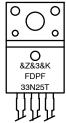
- PDP TV
- Lighting
- Uninterruptible Power Supply
- AC-DC Power Supply

V _{DSS}	R _{DS(on)} MAX	I _D MAX
250 V	94 mΩ @ 10 V	33 A

MARKING DIAGRAM



TO-220 Fullpack, 3-Lead / TO-220F-3SG CASE 221AT





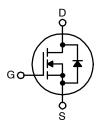
TO-220-3LD LF (LG-formed) CASE 340BL



&Z &3 &K FDPF33N25T Assembly Plant Code3-Digit Date Code

= 2-Digits Lot Run Code 5T = Specific Device Code

N-CHANNEL MOSFET



ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter		FDPF33N25T FDPF33N25TRDTU	Unit
V _{DSS}	Drain-Source Voltage		250	V
I _D	Drain Current	- Continuous (T _C = 25°C) - Continuous (T _C = 100°C)	33* 20.4*	A A
I _{DM}	Drain Current	- Pulsed (Note 1)	132*	Α
V _{GSS}	Gate-Source Voltage		±30	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		918	mJ
I _{AR}	Avalanche Current (Note 1)		33	Α
E _{AR}	Repetitive Avalanche Energy (Note 1)		23.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5	V/ns
P _D	Power Dissipation (T _C = 25°C) – Derate Above 25°C		37 0.29	W W/°C
T _{J,} T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. *Drain current limited by maximum junction temperature.

1. Repetitive rating: pulse–width limited by maximum junction temperature.
2. L = 1.35 mH, $I_{AS} = 33$ A, $V_{DD} = 50$ V, $P_{CD} = 25$ P_{CD} , starting $P_{CD} = 25$ P_{CD} .
3. $P_{CD} = 33$ A, $P_{$

THERMAL CHARACTERISTICS

Symbol	Parameter	FDPF33N25T FDPF33N25TRDTU	Unit
$R_{ heta JC}$	Thermal Resistance, Junction-to-Case, Max.	3.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
OFF CHAP	ACTERISTICS	•				
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}, T_J = 25^{\circ}\text{C}$	250	-	_	V
$\begin{array}{c} \Delta BV_{DSS} \\ / \Delta T_J \end{array}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	-	0.25	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 250 V, V _{GS} = 0 V V _{DS} = 200 V, T _C = 125°C		- -	1 10	μ Α μ Α
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V	-	-	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{V}$	-	-	-100	nA
ON CHAR	ACTERISTICS	•				
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	3.0	_	5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 16.5 A	-	0.077	0.094	Ω
9FS	Forward Transconductance	V _{DS} = 40 V, I _D = 16.5 A	-	26.6	_	S
DYNAMIC	CHARACTERISTICS					
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1.0 \text{ MHz}$	-	1640	2135	pF
C _{oss}	Output Capacitance		-	330	430	pF
C _{rss}	Reverse Transfer Capacitance		-	39	59	pF
SWITCHIN	G CHARACTERISTICS					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 125 \text{ V}, I_D = 33 \text{ A}, V_{GS} = 10 \text{ V},$	-	35	80	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$ (Note 4)	-	230	470	ns
t _{d(off)}	Turn-Off Delay Time]	-	75	160	ns
t _f	Turn-Off Fall Time]	-	120	250	ns
Q_g	Total Gate Charge	V _{DS} = 200 V, I _D = 33 A, V _{GS} = 10 V	-	36.8	48	nC
Q_{gs}	Gate-Source Charge	(Note 4)	-	10	-	nC
Q_{gd}	Gate-Drain Charge]	-	17	_	nC
DRAIN-SC	DURCE DIODE CHARACTERISTICS AND MAX	KIMUM RATINGS				
I _S	Maximum Continuous Drain-Source Diode Forward Current		-	_	33	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forwar	d Current	-	-	132	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 33 A	-	-	1.4	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_S = 33 \text{ A,}$	-	220	-	ns
Q_{rr}	Reverse Recovery Charge	$dl_{F}/dt = 100 A/\mu s$	-	1.71	_	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

TYPICAL PERFORMANCE CHARACTERISTICS

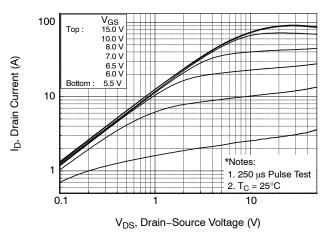


Figure 1. On-Region Characteristics

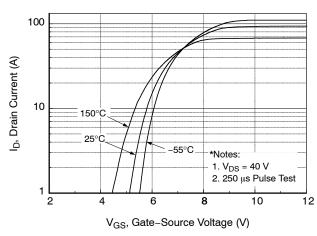


Figure 2. Transfer Characteristics

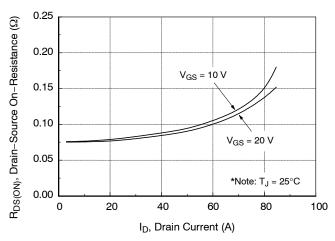


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

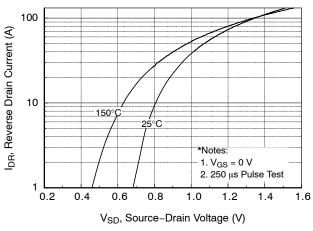


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

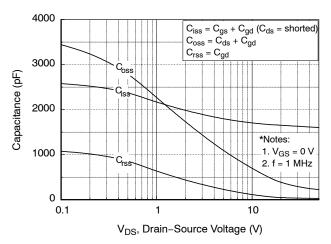


Figure 5. Capacitance Characteristics

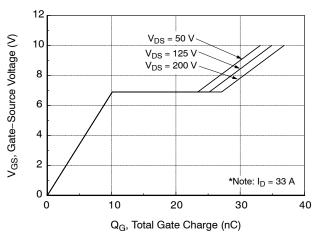
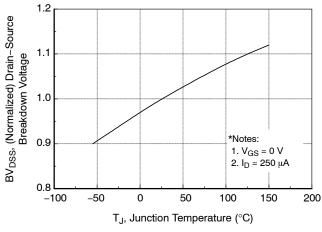


Figure 6. Gate Charge Characteristics

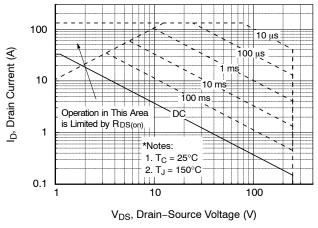
TYPICAL PERFORMANCE CHARACTERISTICS (Continued)



3.0 R_{DS(ON)}, (Normalized) Drain-Source 2.5 On-Resistance 2.0 1.5 1.0 *Notes: 0.5 1. $V_{GS} = 10 \text{ V}$ 2. I_D = 16.5 A 0.0 100 100 150 200 T_J, Junction Temperature (°C)

Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



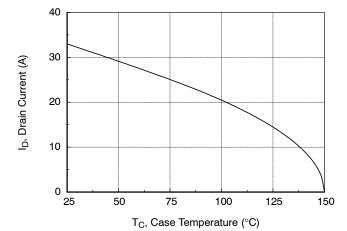


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

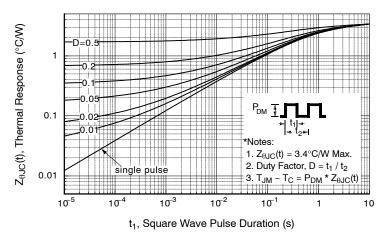


Figure 11. Transient Thermal Response Curve

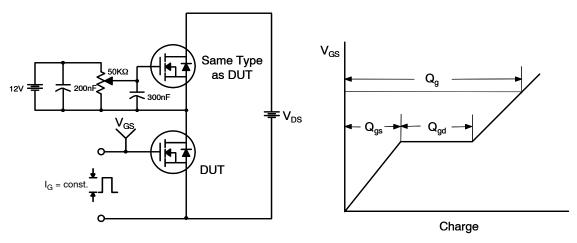


Figure 12. Gate Charge Test Circuit & Waveform

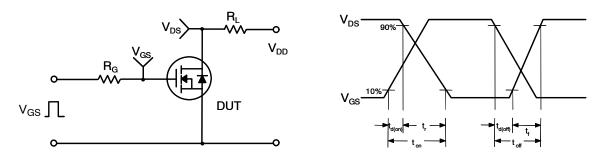


Figure 13. Resistive Switching Test Circuit & Waveforms

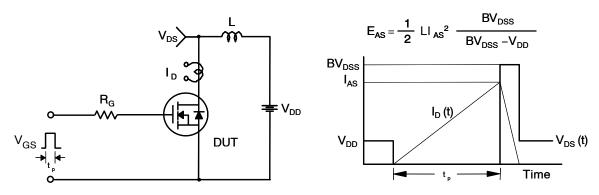
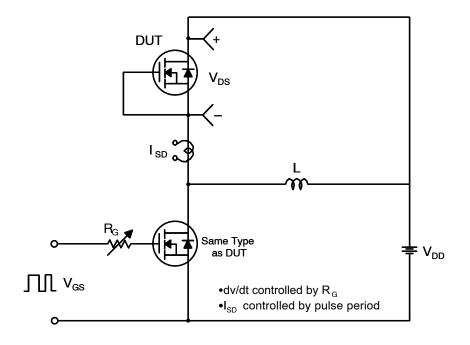


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



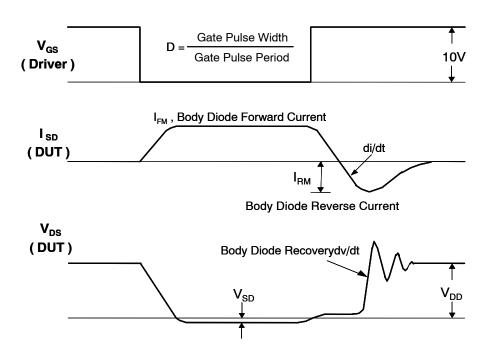
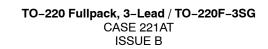


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

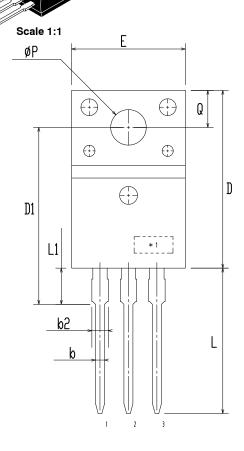
PACKAGE MARKING AND ORDERING INFORMATION

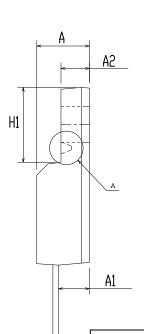
Part Number	Top Mark	Package	Shipping
FDPF33N25T	FDPF33N25T	TO-220 Fullpack, 3-Lead / TO-220F-3SG CASE 221AT	50 Units / Tube
FDPF33N25TRDTU	FDPF33N25T	TO-220-3LD LF (LG-formed) CASE 340BL	50 Units / Tube

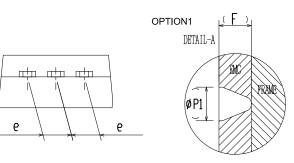
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DATE 19 JAN 2021







DIM	MILLIMITERS			
ויונע	MIN	NDM	MAX	
Α	4.50	4.70	4.90	
A1	2.56	2.76	2.96	
A2	2.34	2.54	2.74	
b	0.70	0.80	0.90	
b2	~	2	1.47	
С	0.45	0.50	0.60	
D	15.67	15.87	16.07	
D1	15.60	15.80	16.00	
E	9.96	10.16	10.36	
е	2.34	2.54	2.74	
F	~	0.84	2	
H1	6.48	6.68	6.88	
L	12.78	12.98	13.18	
L1	3.03	3.23	3.43	
ØΡ	2.98	3.18	3.38	
Ø P1	~	1.00	~	
Q	3.20	3.30	3.40	

MILLIMITEDS

NOTES:

- A. DIMENSION AND TOLERANCE AS ASME Y14.5-2009
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUCSIONS.

C

C. OPTION 1 - WITH SUPPORT PIN HOLE OPTION 2 - NO SUPPORT PIN HOLE

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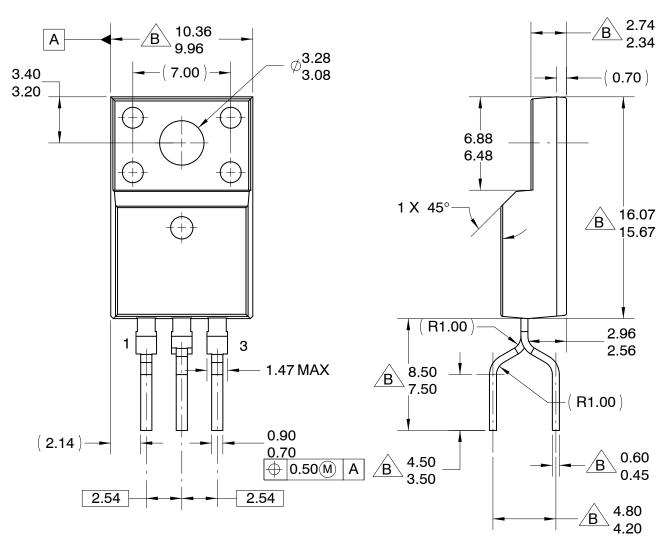
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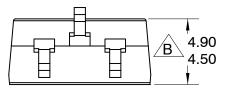
DESCRIPTION: TO-220 FULLPACK, 3-LEAD / TO-220F-3SG PAGE 1 OF 1

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TO-220-3LD LF CASE 340BL ISSUE O

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NOTES:

- A. EXCEPT WHERE NOTED CONFORMS TO EIAJ SC91A.
- B DOES NOT COMPLY EIAJ STD. VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
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